SCT2080KE

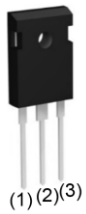
N-channel SiC power MOSFET

Datasheet

V_{DSS}	1200V
$R_{DS(on)}$ (Typ.)	80mΩ
I_D	40A

●Outline

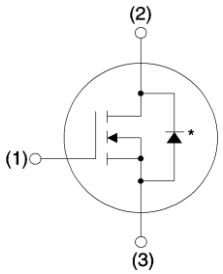
TO-247
TO-247N



●Features

1) Low on-resistance
2) Fast switching speed
3) Fast reverse recovery
4) Easy to parallel
5) Simple to drive
6) Pb-free lead plating ; RoHS compliant

●Inner circuit



(1) Gate
(2) Drain
(3) Source

* Body Diode

●Application

・Solar inverters
・DC/DC converters
・Induction heating
・Motor drives

●Packaging specifications*1

Package		TO-247	TO-247N
Type	Packing	Tube	
	Reel size (mm)	-	
	Tape width (mm)	-	
	Basic ordering unit (pcs)	30	
	Packing code	C	C11
	Marking	SCT2080KE	

●Absolute maximum ratings (T_a = 25°C)

Parameter		Symbol	Value	Unit
Drain - Source voltage		V_{DSS}	1200	V
Continuous drain current	T_c = 25°C	I_D *2	40	A
	T_c = 100°C	I_D *2	28	A
Pulsed drain current		$I_{D,pulse}$ *3	80	A
Gate - Source voltage (DC)		V_{GSS}	−6 to +22	V
Gate - Source surge voltage (t_{surge} < 300nsec)		V_{GSS_surge} *4	−10 to +26	V
Junction temperature		T_j	175	°C
Range of storage temperature		T_{stg}	−55 to +175	°C

●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 1mA	1200	-	-	V
Zero gate voltage drain current	I_{DSS}	V_{DS} = 1200V, V_{GS} = 0V				μA
		T_j = 25°C	-	1	10	
		T_j = 150°C	-	2	-	
Gate - Source leakage current	I_{GSS+}	V_{GS} = +22V, V_{DS} = 0V	-	-	100	nA
Gate - Source leakage current	I_{GSS-}	V_{GS} = -6V, V_{DS} = 0V	-	-	-100	nA
Gate threshold voltage	$V_{GS\ (th)}$	V_{DS} = V_{GS}, I_D = 4.4mA	1.6	2.8	4.0	Ω

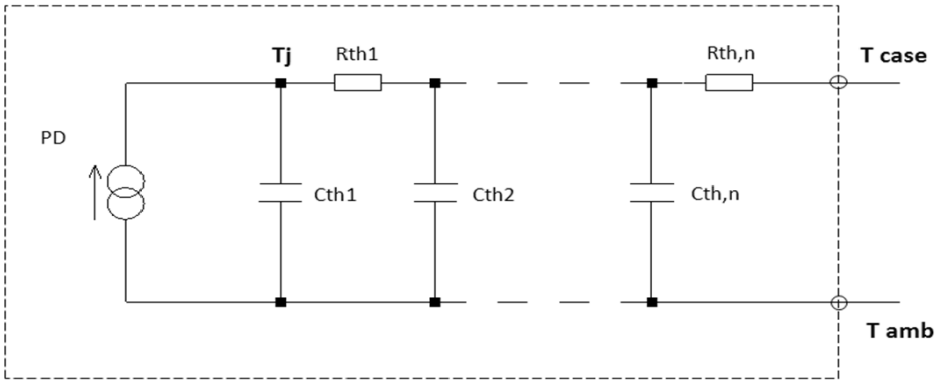
●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}	-	0.44	0.57	°C/W

●Typical Transient Thermal Characteristics

Symbol	Value	Unit
R_{th1}	7.80E-02	K/W
R_{th2}	1.97E-01	
R_{th3}	1.62E-01	

Symbol	Value	Unit
C_{th1}	5.00E-03	Ws/K
C_{th2}	1.80E-02	
C_{th3}	2.49E-01	



●Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Static drain - source on - state resistance	$R_{DS(on)}$ *5	V_{GS} = 18V, I_D = 10A T_j = 25°C	-	80	117	mΩ
		T_j = 125°C	-	125	-	
Gate input resistance	R_G	f = 1MHz, open drain	-	6.3	-	Ω
Transconductance	g_{fs} *5	V_{DS} = 10V, I_D = 10A	-	3.7	-	S
Input capacitance	C_{iss}	V_{GS} = 0V	-	2080	-	pF
Output capacitance	C_{oss}	V_{DS} = 800V	-	77	-	
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	16	-	
Effective output capacitance, energy related	$C_{o(er)}$	V_{GS} = 0V V_{DS} = 0V to 500V	-	116	-	pF
Turn - on delay time	$t_{d(on)}$ *5	V_{DD} = 400V, V_{GS} = 18V	-	35	-	ns
Rise time	t_r *5	I_D = 10A	-	36	-	
Turn - off delay time	$t_{d(off)}$ *5	R_L = 40Ω	-	76	-	
Fall time	t_f *5	R_G = 0Ω	-	22	-	
Turn - on switching loss	E_{on} *5	V_{DD} = 600V, I_D=10A V_{GS} = 18V/0V R_G = 0Ω, L=500μH *E_{on} includes diode reverse recovery	-	174	-	μJ
Turn - off switching loss	E_{off} *5		-	51	-	

●Gate Charge characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g *5	V_{DD} = 400V	-	106	-	nC
Gate - Source charge	Q_{gs} *5	I_D = 10A	-	27	-	
Gate - Drain charge	Q_{gd} *5	V_{GS} = 18V	-	31	-	
Gate plateau voltage	$V_{(plateau)}$	V_{DD} = 400V, I_D = 10A	-	9.7	-	V

●**Body diode electrical characteristics** (Source-Drain) (T_a = 25°C)

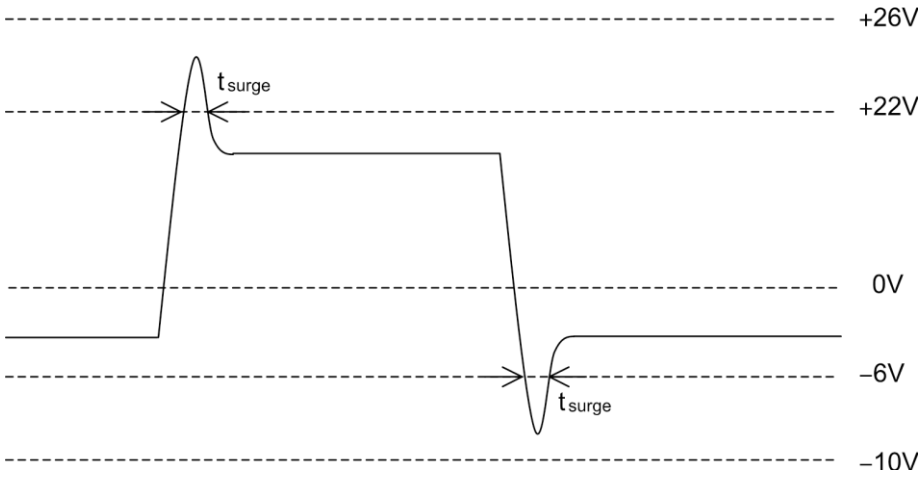
Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Body diode continuous, forward current	I_S *2	T_c = 25°C	-	-	40	A
Body diode direct current, pulsed	I_{SM} *3		-	-	80	A
Forward voltage	V_{SD} *5	V_{GS} = 0V, I_S = 10A	-	4.6	-	V
Reverse recovery time	t_{rr} *5	I_F = 10A, V_R = 400V di/dt = 150A/μs	-	31	-	ns
Reverse recovery charge	Q_{rr} *5		-	44	-	nC
Peak reverse recovery current	I_{rrm} *5		-	2.3	-	A

*1 Tolerances of dimensions and packing specifications slightly differ between TO-247 and TO-247N, which is unlikely to influence compatibility for mounting. Please refer to corresponding specifications of dimensions for more details.

*2 Limited only by maximum temperature allowed.

*3 PW ≤ 10μs, Duty cycle ≤ 1%

*4 Example of acceptable V_{GS} waveform



*5 Pulsed

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

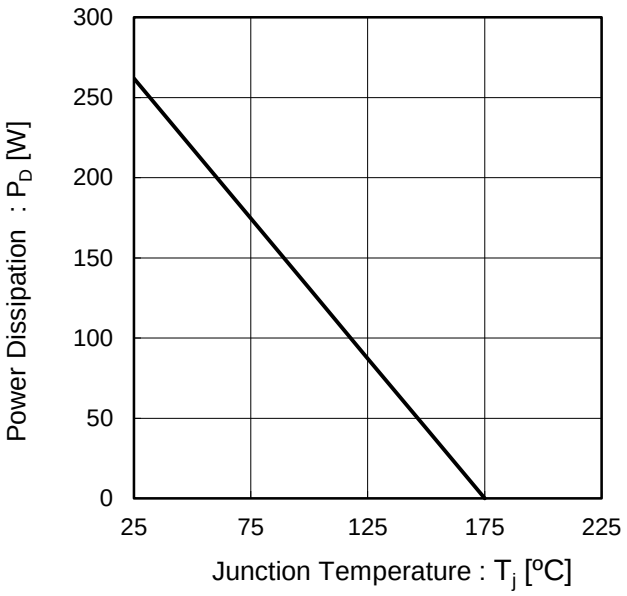


Fig.2 Maximum Safe Operating Area

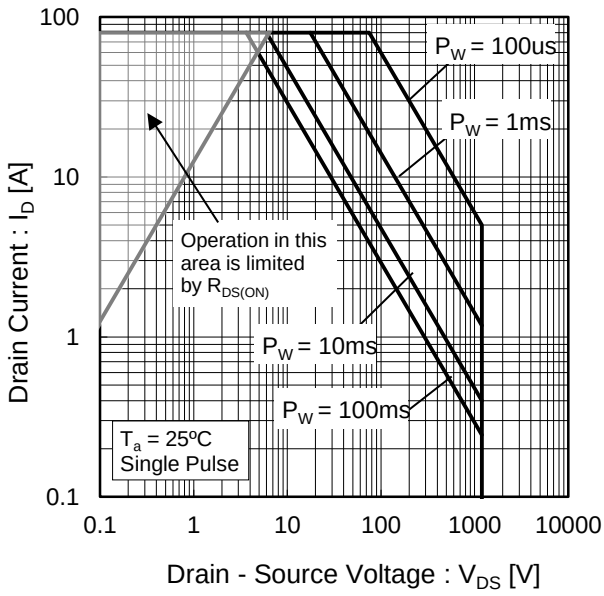
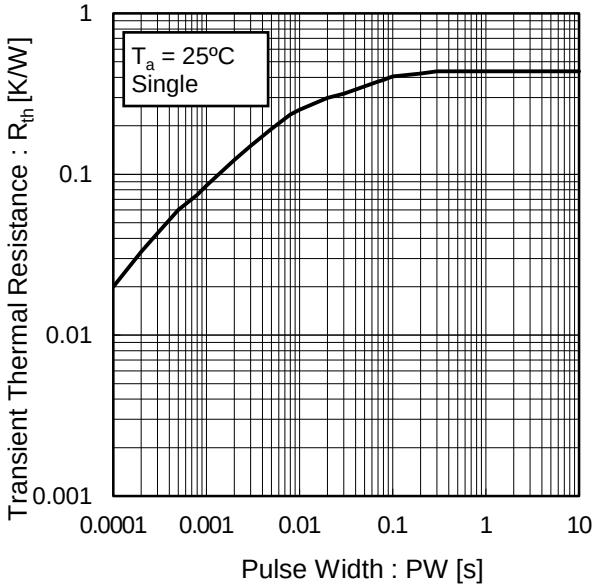


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



●Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)

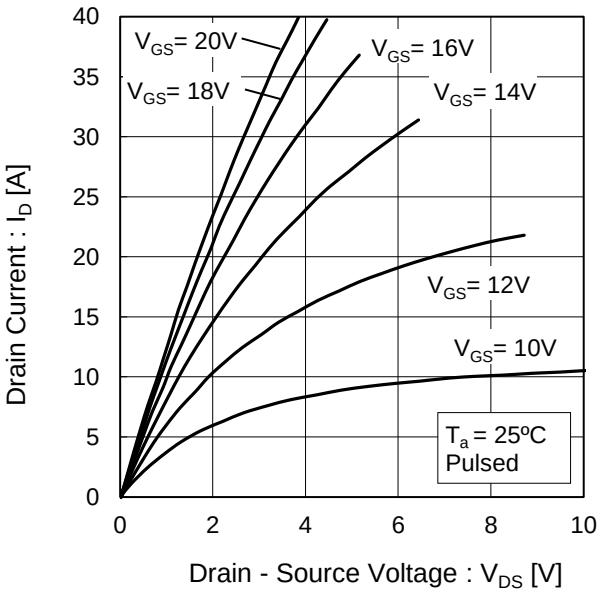


Fig.5 Typical Output Characteristics(II)

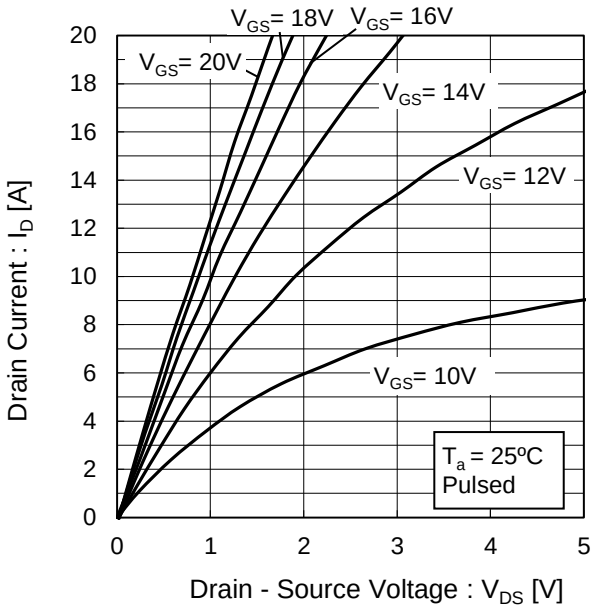


Fig.6 Typical Output Characteristics(I)

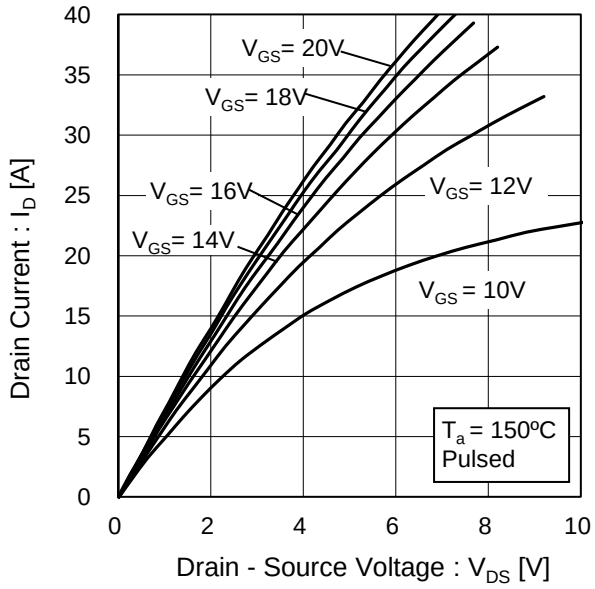
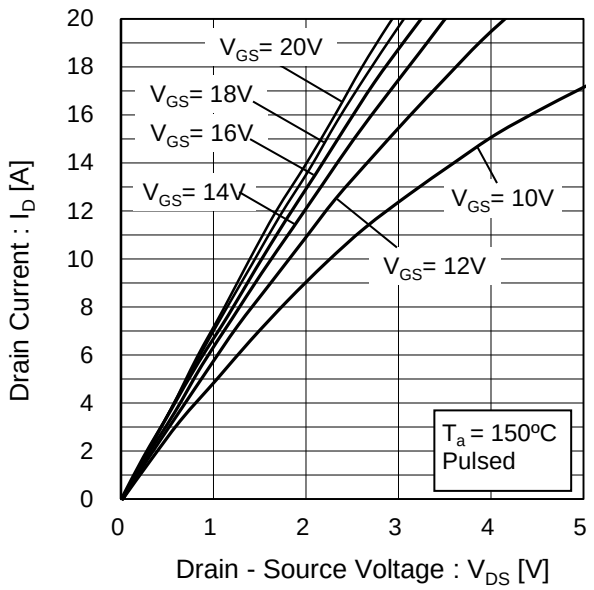


Fig.7 Typical Output Characteristics(II)



●Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

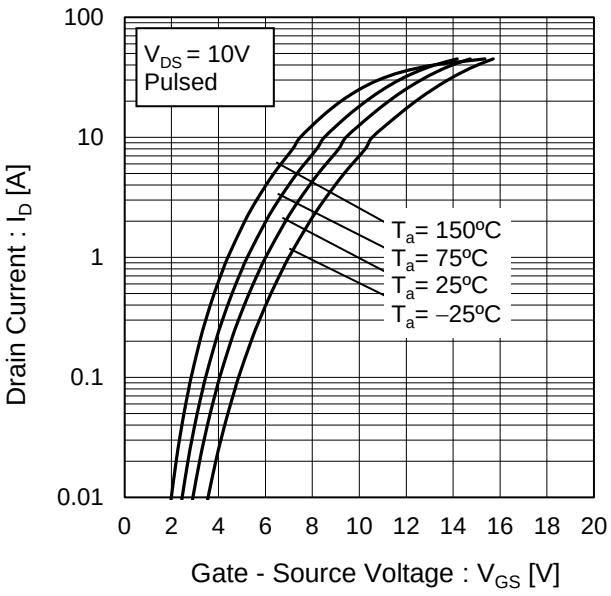


Fig.9 Typical Transfer Characteristics (II)

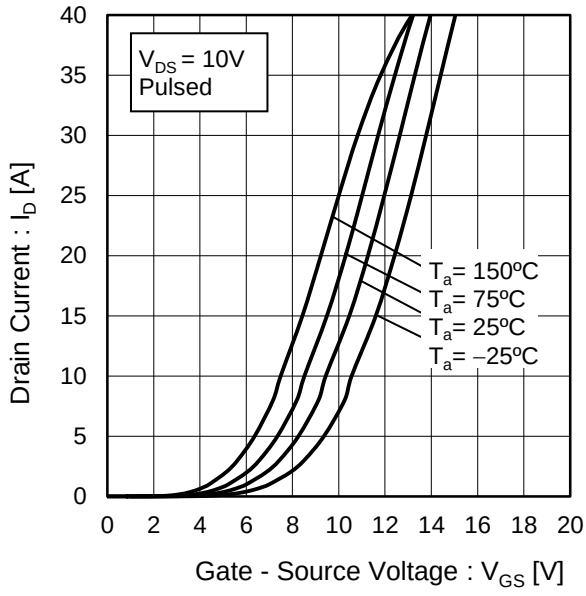


Fig.10 Gate Threshold Voltage vs. Junction Temperature

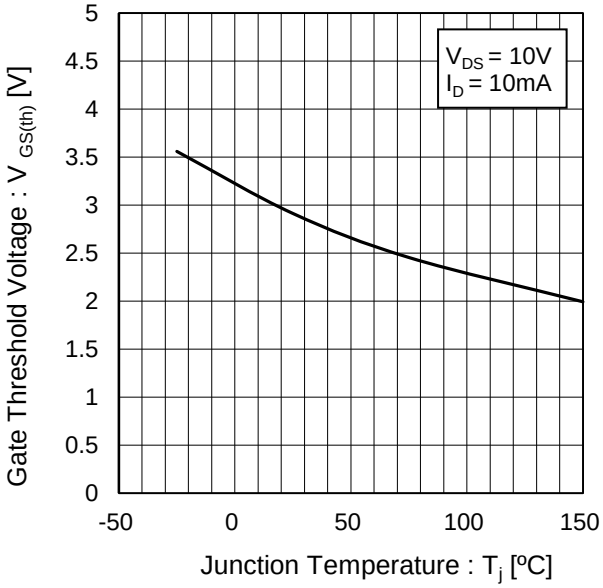
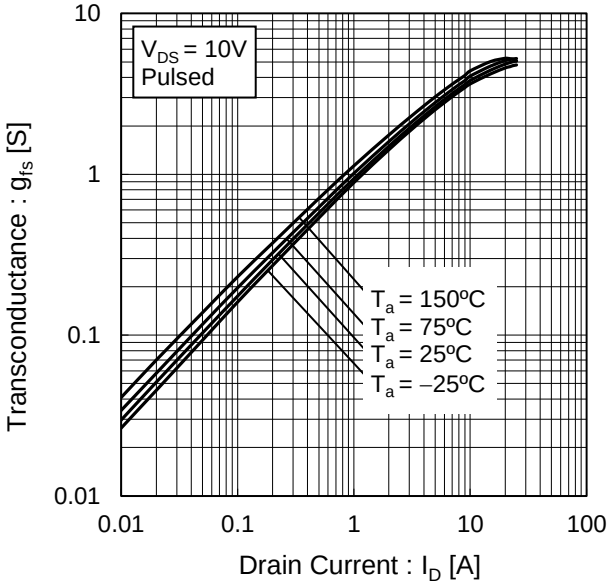


Fig.11 Transconductance vs. Drain Current



●Electrical characteristic curves

Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

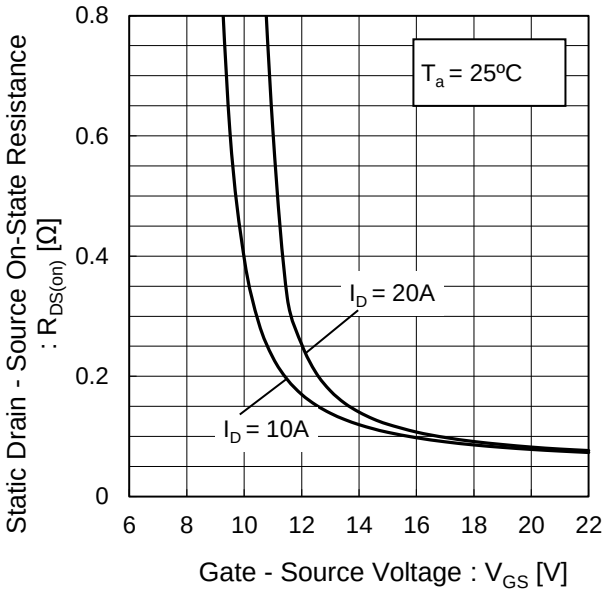


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

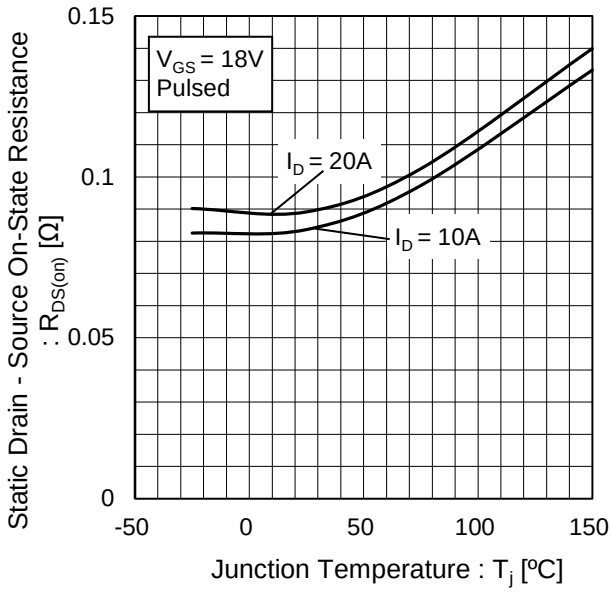
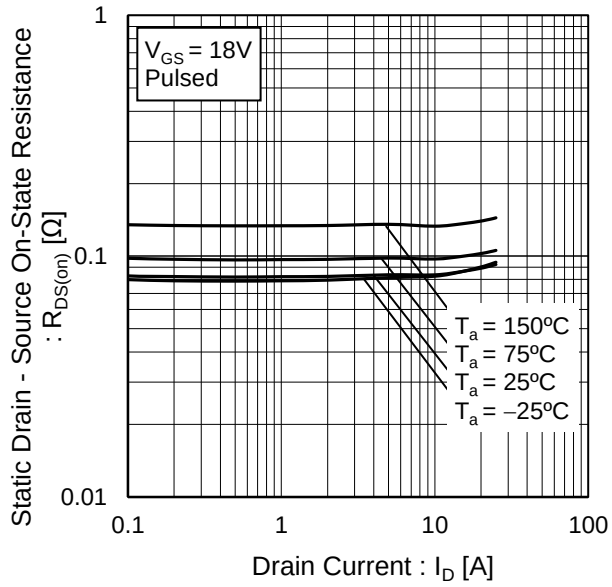


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current



●Electrical characteristic curves

Fig.15 Typical Capacitance vs. Drain - Source Voltage

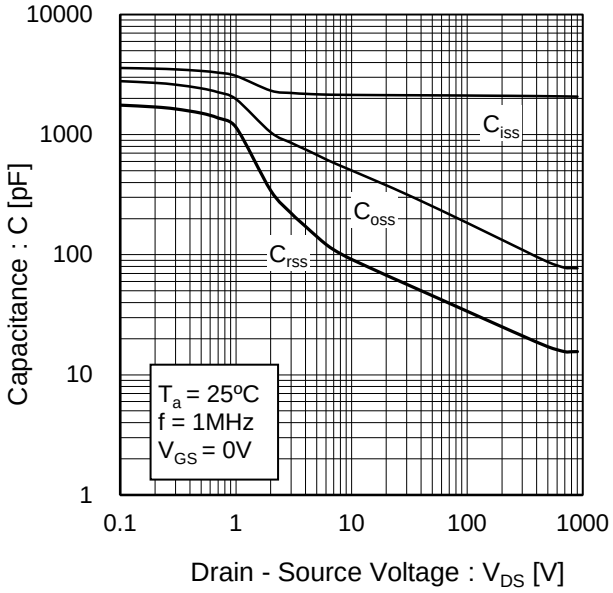


Fig.16 C_{oss} Stored Energy

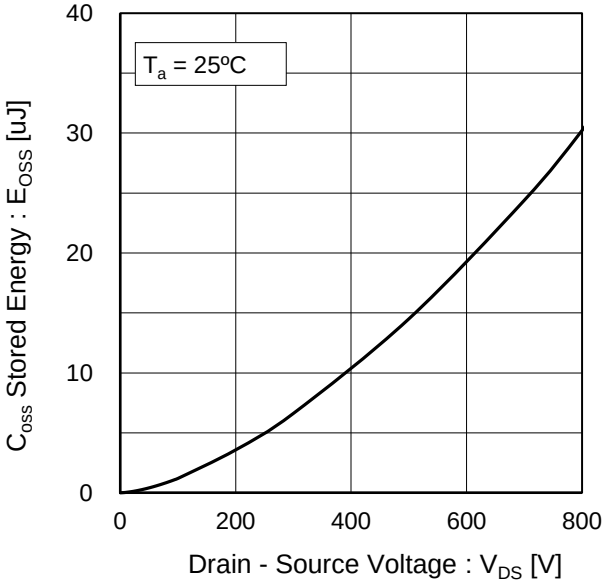


Fig.17 Switching Characteristics

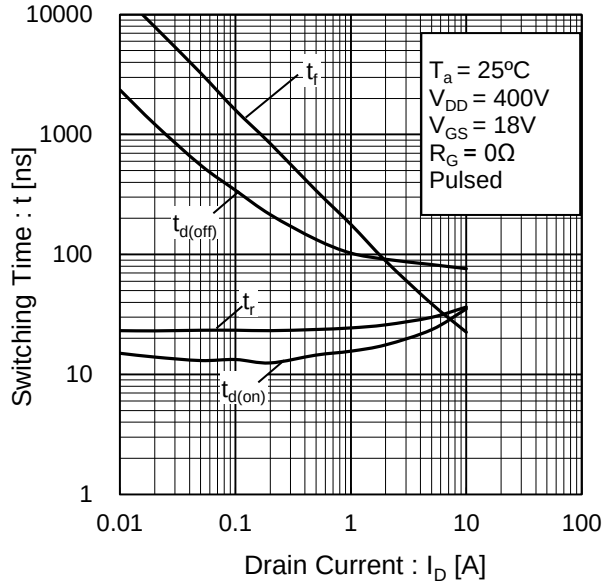
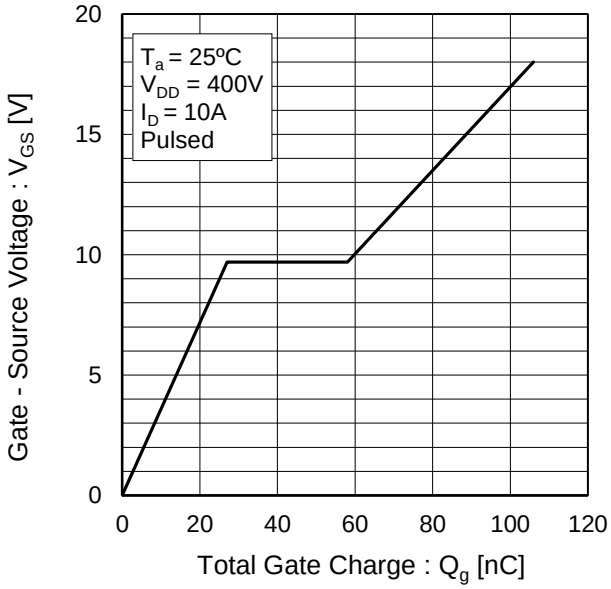


Fig.18 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.19 Typical Switching Loss vs. Drain - Source Voltage

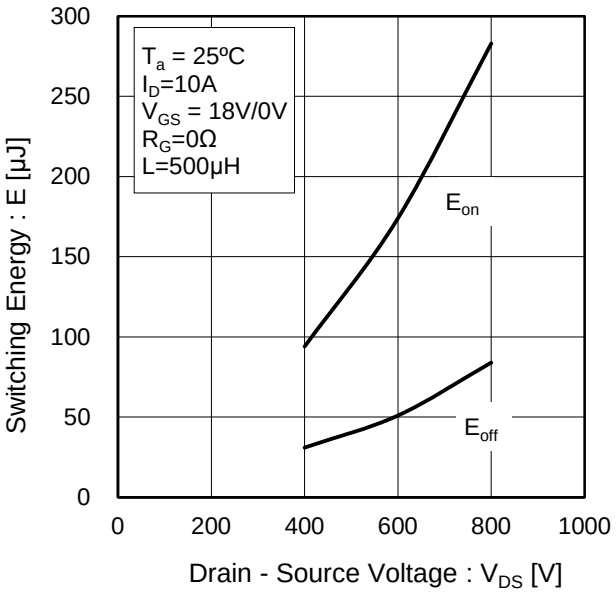


Fig.20 Typical Switching Loss vs. Drain Current

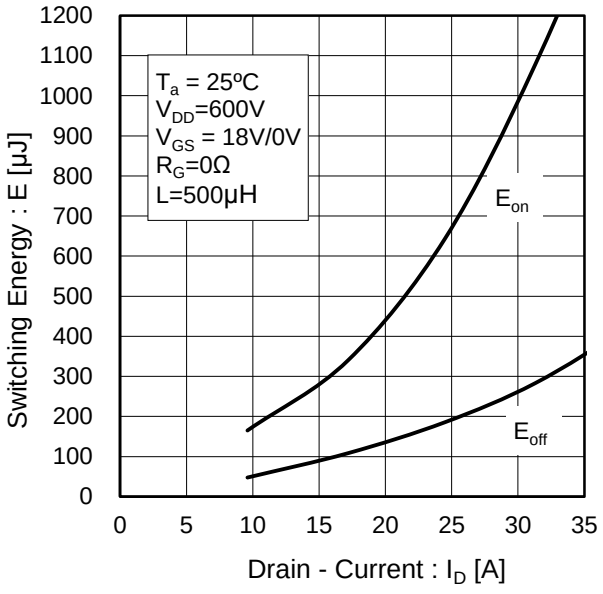
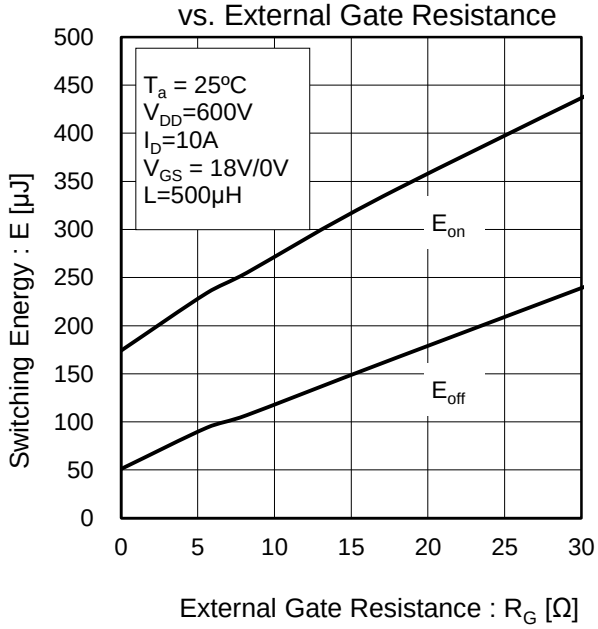


Fig.21 Typical Switching Loss vs. External Gate Resistance



●Electrical characteristic curves

Fig.22 Body Diode Forward Current vs. Source - Drain Voltage

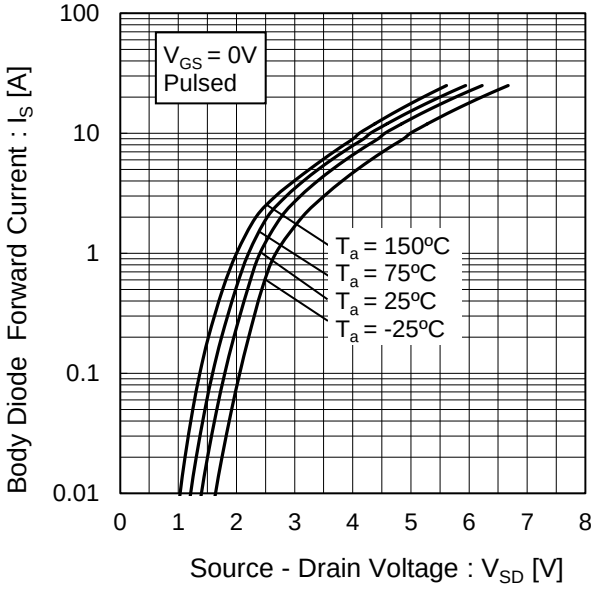
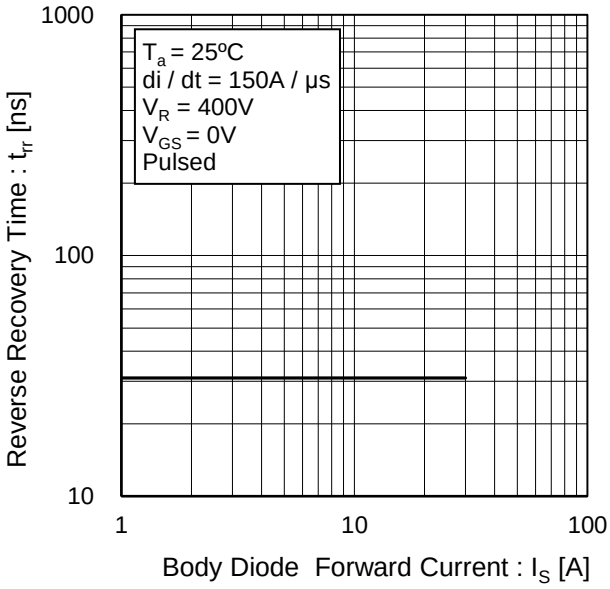


Fig.23 Reverse Recovery Time vs.Body Diode Forward Current



●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

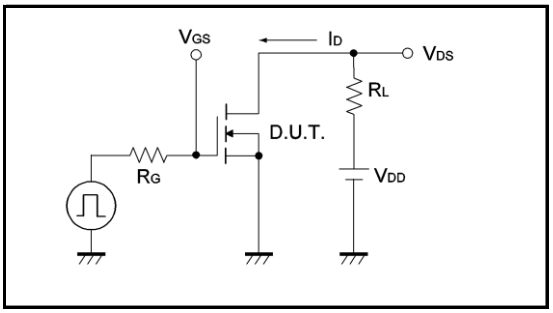


Fig.1-2 Switching Waveforms

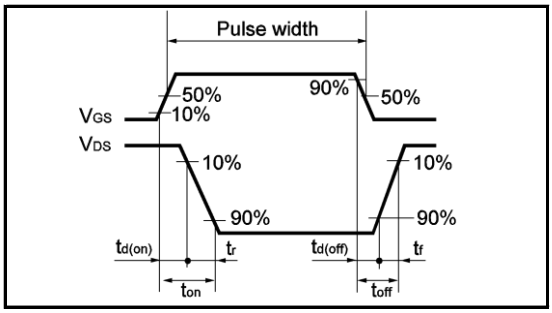


Fig.2-1 Gate Charge Measurement Circuit

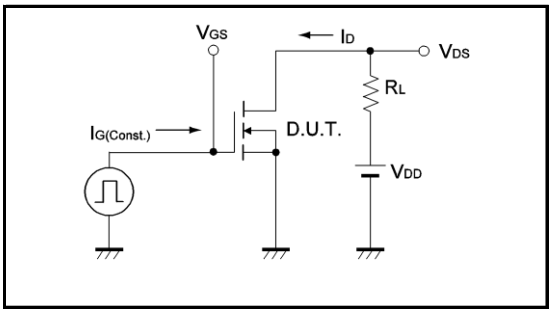


Fig.2-2 Gate Charge Waveform

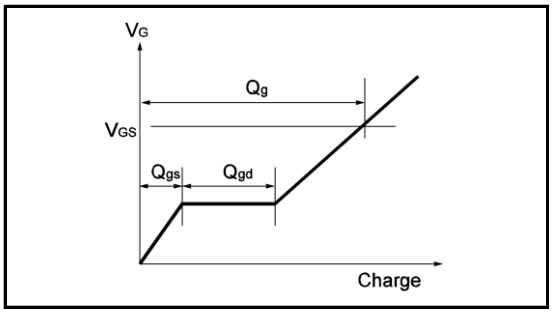


Fig.3-1 Switching Energy Measurement Circuit

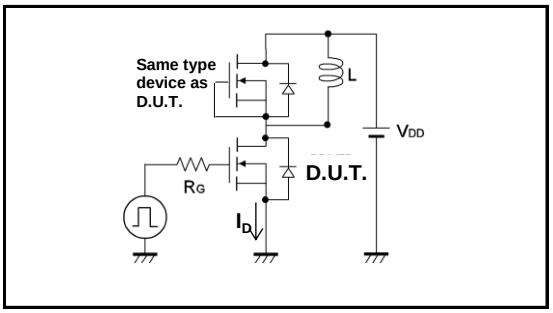


Fig.3-2 Switching Waveforms

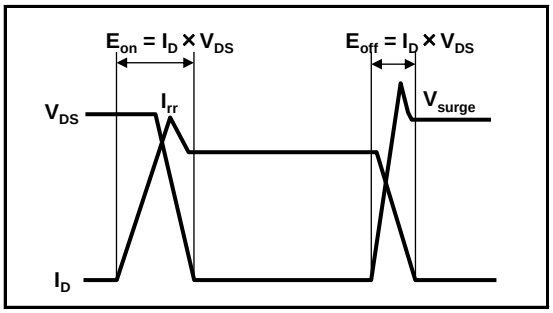


Fig.4-1 Reverse Recovery Time Measurement Circuit

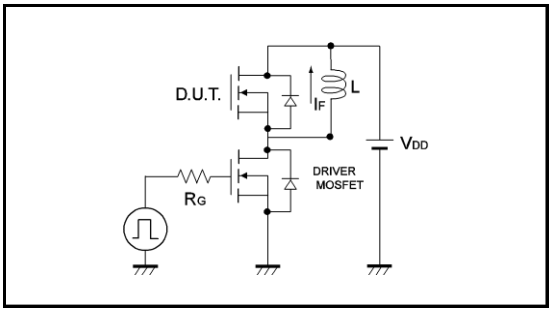
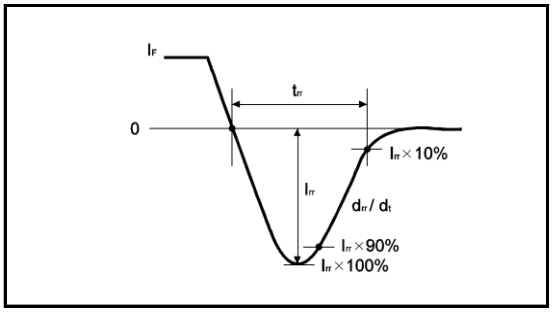


Fig.4-2 Reverse Recovery Waveform



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